I‘M Intelligent Memory introduces their newest revisions of 8 Gigabit DDR3L components.
Orderable devices include x8 (1Gx8) configurations in FBGA 78 ball package and x16 (512Mx16) types in FBGA 96 ball package. Customers can choose the devices to have either a single Chip-Select (1CS) or dual Chip-Select (2CS) pinout.

In addition, I’M offers a 8Gb device in a x4 (2Gx4) configuration in FBGA 78 ball package, suitable to manufacture DDR3L RDIMM or LRDIMM modules for servers, which have been announced EOL by most of the large memory manufacturers.

All I’M 8Gb devices support DDR3L low-voltage (1.35V) operation and are fully backward-compatible to standard DDR3 1.5V operation. The products are optionally available in commercial (0°C ~ +95°C) as well as industrial temperature (-40°C ~ 95°C) ranges.

With dimensions of only 9x10.6mm for the FBGA78 and 9x13.5mm for the FBGA96 package, the devices are small enough to fit on a majority of existing layouts.

Based on these new 8Gb x8 1CS components, I’M is also releasing a revision update for their 16 Gigabyte DDR3L UDIMM and SO-DIMM memory modules with optional ECC error-correction. Utilizing the 8Gb x8 2CS devices, I’M manufactures VLP RDIMM as well as VLP Mini RDIMMs.

For more information and to request samples please visit www.intelligentmemory.com or contact our sales team directly!

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